

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 06097614
PUBLICATION DATE : 08-04-94

APPLICATION DATE : 10-09-92
APPLICATION NUMBER : 04242329

APPLICANT : MITSUBISHI SHINDOH CO LTD;

INVENTOR : ISHIKAWA TETSUYA;

INT.CL. : H05K 1/03 B32B 15/08

TITLE : MULTILAYER BOARD

ABSTRACT : PURPOSE: To prevent the peeling of a copper layer and the deformation of a board due to temperature change, and facilitate the recycling of resin, by arranging a resin plate made of liquid crystal polymer whose thermal expansion coefficient has a specified value and a copper layer or a copper alloy layer which are formed on the resin plate and have copper contents larger than or equal to a specified value.

CONSTITUTION: An oxygen-free copper foil (Cu: 99.99%, O₂: 100ppm or less) of thickness 0.07mm, width 250mm and length 5000mm is bonded to a resin plate by using epoxy based adhesive agent, thereby forming a multilayer board. As the resin plate, a plate member of thickness 3mm, width 250mm and length 500mm is used which is composed of aromatic polyester being liquid crystal polymer. The thermal expansion coefficient of a conducting layer is $17.0 \times 10^{-6}/^{\circ}\text{C}$, and that of a resin board is $16.2 \times 10^{-6}/^{\circ}\text{C}$. Thereby the peeling of a copper layer and the deformation of a board can be prevented, and the recycling of resin is facilitated.

COPYRIGHT: (C)1994,JPO&Japio